Twin Build in Biasing Circuit MOS FET IC VHF/UHF RF Amplifier

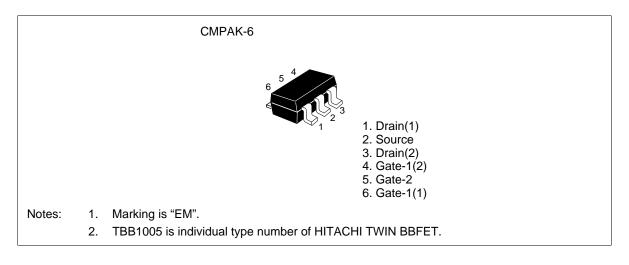
HITACHI

ADE-208-989F (Z) Preliminary 7th. Edition Dec. 2000

Features

- Small SMD package CMPAK-6 built in twin BBFET; To reduce using parts cost & PC board space.
- Suitable for World Standard Tuner RF amplifier.
- Very useful for total tuner cost reduction.
- Withstanding to ESD; Build in ESD absorbing diode. Withstand up to 200 V at C = 200 pF, Rs = 0 conditions.
- Provide mini mold packages; CMPAK-6

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	6	V	
Gate1 to source voltage	V _{G1S}	+6 -0	V	
Gate2 to source voltage	V _{G2S}	+6 -0	V	
Drain current	I _D	30	mA	
Channel power dissipation	Pch ^{*3}	250	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 3. Value on the glass epoxy board ($49mm \times 38mm \times 1mm$).

Electrical Characteristics (Ta = 25°C)

The below specification are applicable for UHF unit (FET1)

Item	Symbol	Min	Тур	Мах	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	6	_	_	V	$I_{\rm D} = 200 \mu A, V_{\rm G1S} = V_{\rm G2S} = 0$
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	_	_	V	I_{G1} = +10µA, V_{G2S} = V_{DS} = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	_	_	V	I_{G2} = +10µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I _{G1SS}	—		+100	nA	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0$
Gate2 to source cutoff current	I _{G2SS}	—		+100	nA	$V_{G2S} = +5V, V_{G1S} = V_{DS} = 0$
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.5	0.75	1.0	V	$V_{\rm DS} = 5V, V_{\rm G2S} = 4V, I_{\rm D} = 100 \mu A$
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.5	0.75	1.0	V	$V_{\rm DS} = 5V, V_{\rm G1S} = 5V, I_{\rm D} = 100 \mu A$
Drain current	I _{D(op)}	13	17	21	mA	$V_{\rm DS} = 5V, V_{\rm G1} = 5V$ $V_{\rm G2S} = 4V, R_{\rm G} = 100 k\Omega$
Forward transfer admittance	y _{fs}	21	26	31	mS	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V$ $R_{G} = 100k\Omega, f = 1kHz$
Input capacitance	C _{iss}	1.4	1.8	2.2	pF	$V_{\rm DS} = 5V, V_{\rm G1} = 5V$
Output capacitance	C _{oss}	1.0	1.4	1.8	pF	V_{G2S} =4V, R_{G} = 100k Ω
Reverse transfer capacitance	C _{rss}	_	0.02	0.04	pF	f = 1MHz
Power gain	PG	16	21	_	dB	$V_{DS} = V_{G1} = 5V, V_{G2S} = 4V$ $R_{G} = 100k\Omega, f = 900MHz$ $Zi=S11^{*}, Zo=S22^{*}(:PG)$
Noise figure	NF		1.7	2.5	dB	Zi=S11opt (:NF)

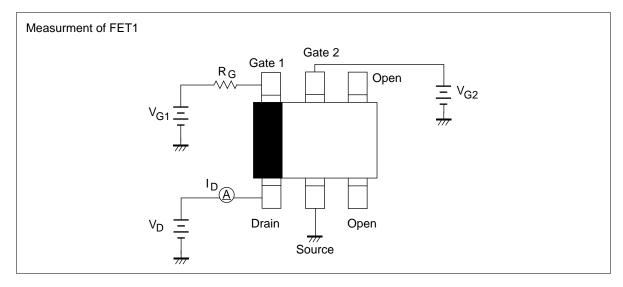
Electrical Characteristics (Ta = 25°C)

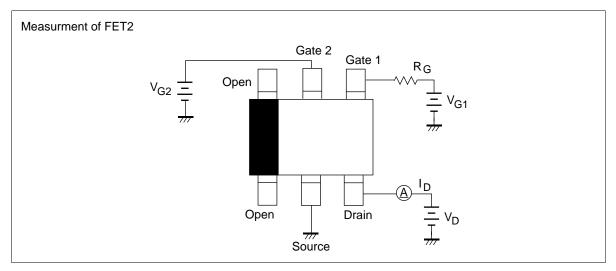
The below specification are applicable for VHF unit (FET2)

Item	Symbol	Min	Тур	Мах	Unit	Test Conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	6	_	_	V	$I_{\rm D} = 200 \mu A, V_{\rm G1S} = V_{\rm G2S} = 0$
Gate1 to source breakdown voltage	$V_{\rm (BR)G1SS}$	+6	_	_	V	I_{G1} = +10µA, V_{G2S} = V_{DS} = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	_	_	V	I_{G2} = +10µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I _{G1SS}	—	—	+100	nA	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0$
Gate2 to source cutoff current	I _{G2SS}	—	_	+100	nA	$V_{G2S} = +5V, V_{G1S} = V_{DS} = 0$
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.5	0.75	1.0	V	$V_{\rm DS} = 5V, V_{\rm G2S} = 4V, I_{\rm D} = 100 \mu A$
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.5	0.75	1.0	V	$V_{\text{DS}} = 5V, V_{\text{G1S}} = 5V, I_{\text{D}} = 100 \mu A$
Drain current	I _{D(op)}	14	18	22	mA	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V, R_{G} = 82k\Omega$
Forward transfer admittance	y _{fs}	20	25	30	mS	$V_{_{DS}} = 5V, V_{_{G1}} = 5V, V_{_{G2S}} = 4V,$ $R_{_{G}} = 82k\Omega, f = 1kHz$
Input capacitance	C _{iss}	2.2	2.6	3.0	pF	$V_{\rm DS} = 5V, V_{\rm G1} = 5V$
Output capacitance	C _{oss}	1.2	1.6	2.0	pF	V_{G2S} =4V, R_{G} = 82k Ω
Reverse transfer capacitance	C _{rss}	—	0.03	0.05	pF	f = 1MHz
Power gain	PG	22	27	—	dB	$V_{\rm DS} = V_{\rm G1} = 5V, V_{\rm G2S} = 4V$
Noise figure	NF	_	1.2	1.7	dB	$R_{\rm G}$ = 82k Ω , f = 200MHz

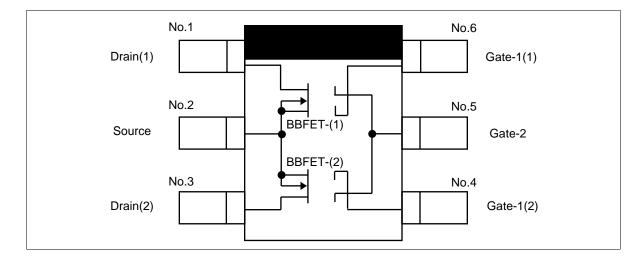
Test Circuits

• DC Biasing Circuit for Operating Characteristic Items (I_{D(op)}, |yfs|, Ciss, Coss, Crss, NF, PG)

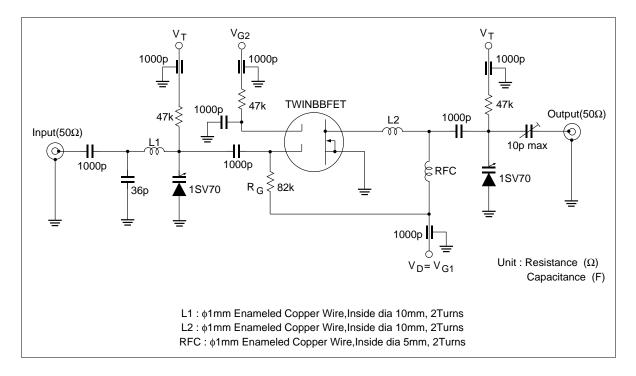


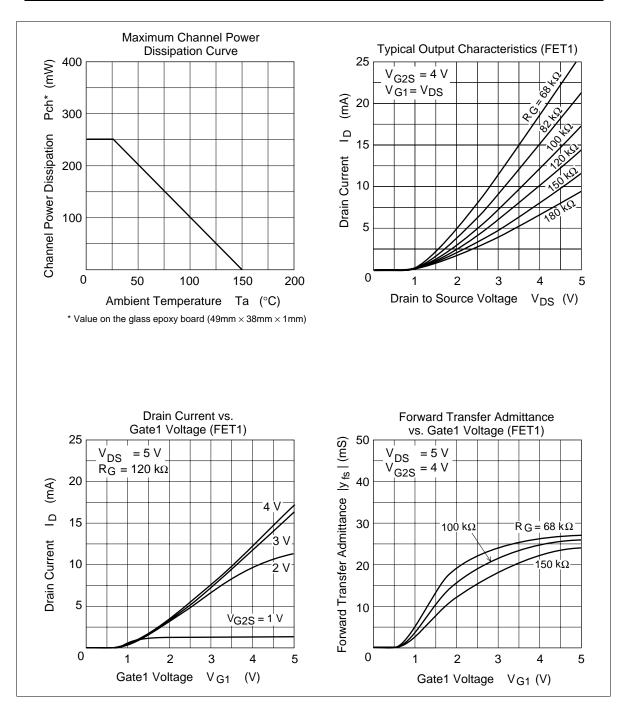


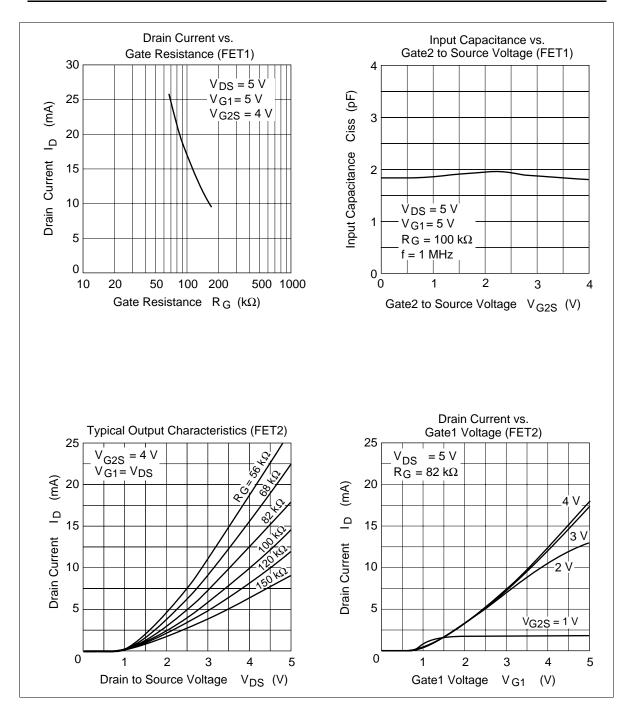
• Equivalent Circuit

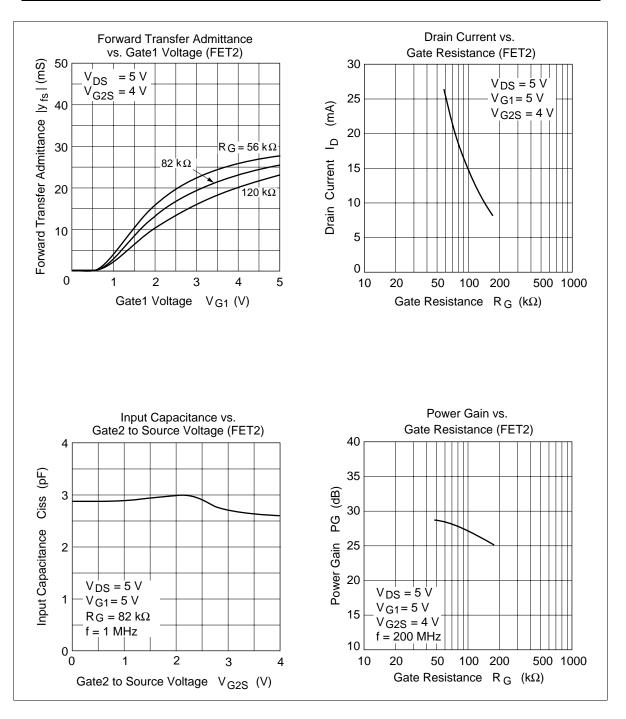


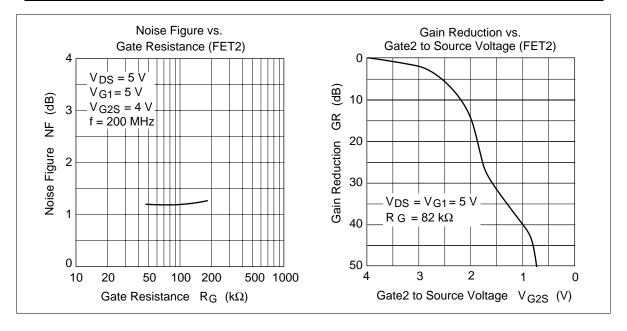
• 200 MHz Power Gain, Noise Figure Test Circuit



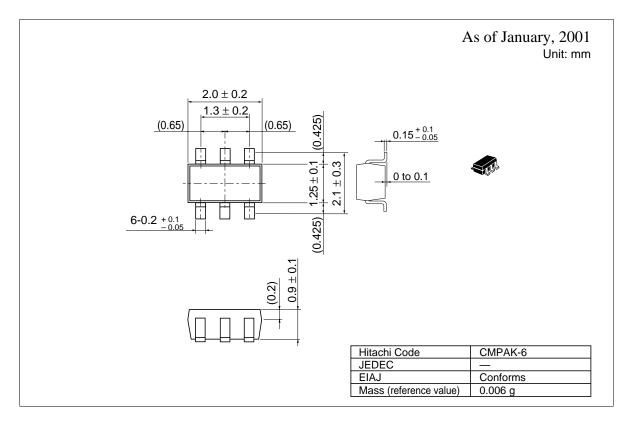








Package Dimensions



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